

the beam path of the light, reflects onto the sensor some of a light beam emitted by the light emitting or light receiving element.

45.
40.

The method for producing an optoelectronic component according to Claim 39, wherein a plurality of auxiliary carriers, which are to be separated in a further process step, are connected jointly in a composite structure with independent sensors and/or with the elements to be connected thereto.

46.
41.

The method for producing an optoelectronic component according to Claim 39, wherein the optical arrangement is bonded into the opening by means of a bonding or adhesive agent.

47.
42.

The method for producing an optoelectronic component according to Claim 39, wherein the system carrier, with the auxiliary carrier attached thereto and the light emitting or light receiving element located thereon, is potted or moulded at least in some areas with a non-transparent pressing, casting or moulding mass.

REMARKS

To reduce initial filing fees and place the claims in U.S. format, claims 1-21 have been cancelled without prejudice, and claims 22-42 have been added. No new matter has been added.

Early consideration and allowance of the application are earnestly solicited.

Respectfully submitted,



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